



Material Content Data Sheet



Halogen-Free

Sales Product Name	IPB65R660CFDA	Issued	24. June 2021
MA#	MA001219552		
Package	PG-TO263-3-2	Weight*	1558.38 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.294	0.21	0.21	2114	2114
leadframe	inorganic material	phosphorus	7723-14-0	0.091	0.01		59	
	non noble metal	iron	7439-89-6	0.304	0.02		195	
	non noble metal	copper	7440-50-8	304.026	19.51	19.54	195090	195344
wire	non noble metal	aluminium	7429-90-5	0.953	0.06	0.06	612	612
encapsulation	inorganic material	zinc oxide	1314-13-2	6.885	0.44		4418	
	miscellaneous	miscellaneous	-	27.538	1.77		17671	
	plastics	epoxy resin	-	103.268	6.63		66266	
	inorganic material	silicon dioxide	60676-86-0	550.762	35.35	44.19	353418	441773
lead finish	non noble metal	tin	7440-31-5	9.657	0.62	0.62	6197	6197
plating	inorganic material	phosphorus	7723-14-0	0.001			1	
	non noble metal	nickel	7440-02-0	0.228	0.01	0.01	147	148
solder	non noble metal	tin	7440-31-5	0.060			38	
	noble metal	silver	7440-22-4	0.075			48	
	non noble metal	lead	7439-92-1	2.863	0.18	0.18	1837	1923
heatspreader	inorganic material	phosphorus	7723-14-0	0.165	0.01		106	
	non noble metal	iron	7439-89-6	0.548	0.04		352	
	non noble metal	copper	7440-50-8	547.666	35.14	35.19	351431	351889
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com